



Innovative Materials Shift the Future

TIANJIN BOYUAN NEW MATERIALS CO., LTD.

Tel: +86-22-83711776/23859962

Fax: +86-22-83711387

E-mail: [BHLT@boyuanmaterials.com](mailto:BHLT@boyuanmaterials.com)

[www.boyuanmaterials.com](http://www.boyuanmaterials.com)

## Hot Melt Adhesive Tape/B6808

### ◆ Brief Introduction:

BOYUAN Hot Melt Adhesive Tape B6808 is special developed for encapsulating IC card. With excellent bonding strength, anti-torsion performance and aging resistance. It is fully compatible to encapsulate module to PVC or ABS card.

### ◆ Structure:

Structure	composition	color	Thickness (μm)
Glue Layer	Modified Polyamide	Semi-transparent	55±5
Release Liner	Glassine Paper	Semi-transparent	70±5

### ◆ Technical Parameters:

Item	Parameters
Pressure (MPa)	0.4~0.6
Pre-welding Temperature (°C)	140~160
Pre-welding Time (s)	0.5~0.6
Encapsulation Temperature (°C)	150~170
Encapsulation Time (s)	0.8~1.2
Bonding Strength (N)	>100
Torsion Test (time) GB/T 17554.1-2006	>2000

### ◆ Packing:

Outer: Carton      Inner: PE bag

### ◆ Storage:

Keep package sealed, 0~30°C, ≤60% RH, Avoid direct sunlight.

Shelf life: two years.

### ◆ Notice:

Gentle load, No press.

In order to avoid overflow and poor bonding strength please choose the proper parameters according to your machine setting.

---

! The information is based on our practical production and result of testing. We suggest testing should be necessary before a batch use. We announce that the specification can not be used as the guarantee of the products.